

IN THE CLAIMS

Amend the claims as follows:

1. (Previously Presented) A method of manufacturing an electronic part in which at least one circuit element is formed on a surface of a ceramic substrate and conductive balls are used as terminals of the electronic part, comprising:

a first step of forming at least one circuit element on the surface of a large ceramic substrate including division grooves longitudinally and laterally provided on the surface thereof;

a second step of fixing the conductive balls to terminal portions of the circuit element; and

a third step of applying stress to the large ceramic substrate to open the division grooves, to divide the substrate, the first, second, and third steps being performed in the stated order,

wherein the stress to be applied in the third step is substantially equally applied to a large number of conductive balls, or the stress is applied to the substrate and/or the circuit element, or a part of the stress is substantially equally applied to a large number of conductive balls and a remainder of the stress is applied to the substrate and/or the circuit element.

2. (Cancelled)

3. (Previously Presented) A method of manufacturing an electronic part according to claim 1 , wherein the third step is performed in a state in which a buffer member having a concave portion is located on the surface of the large ceramic substrate to which conductive balls are fixed to house the conductive balls in the concave portion and a portion of the buffer member which becomes a convex portion relative to a presence of the concave portion is on contact with the surface of the substrate and/or the circuit element.

4. (Previously Presented) A method of manufacturing an electronic part according to claim 1 , wherein the division grooves exist on the surface of the substrate to which conductive balls are fixed.

5. (Cancelled).

6. (Previously Presented) A method of manufacturing an electronic part according to claim 1 , wherein the conductive balls are fixed to the substrate using a conductive bonding agent.

7. (Previously Presented) A method of manufacturing an electronic part in which at least one circuit element is formed on a surface of a ceramic substrate and conductive balls are used as terminals of the electronic part, comprising:

a first step of forming at least one circuit element on the surface of a large ceramic substrate;

a second step of fixing the conductive balls to terminal portions of the circuit element;

a third step of forming division grooves for the large ceramic substrate on the surface of the substrate on which the circuit element exists; and

a fourth step of applying stress to the large ceramic substrate to open the division grooves, to divide the substrate, the first, second, third and fourth steps being performed in the stated order,

wherein the stress to be applied in the fourth step is substantially equally applied to a large number of conductive balls, or the stress is applied to the substrate and/or the circuit element, or a part of the stress is substantially equally applied to a large number of conductive balls and a remainder of the stress is applied to the substrate and/or the circuit element.

8. (Previously Presented) A method of manufacturing an electronic part according to claim 7, wherein the fourth step is performed in a state in which a buffer member having a concave portion is located on the surface of the large ceramic substrate to which conductive balls are fixed to house the conductive balls in the concave portion and a portion of the buffer member which becomes a convex portion relative to a presence of the concave portion is on contact with the surface of the substrate and/or the circuit element.

9. (Previously Presented) A method of manufacturing an electronic part according to claim 7, wherein the division grooves exist on the surface of the substrate to which conductive balls are fixed.

10. (Previously Presented) A method of manufacturing an electronic part according to claim 7, wherein the conductive balls are fixed to the substrate using a conductive bonding agent.

11. (New) A method of manufacturing an electronic part according to claim 1, wherein the division grooves exist on the surface of the substrate on which the circuit element is formed.